

50 mA, 100 mA, and 150 mA CMOS LDOs with Shutdown and Error Output

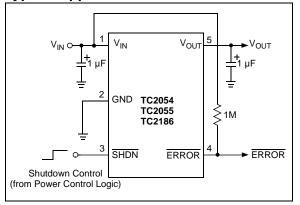
Features

- Low Supply Current (55 µA Typical) for Longer Battery Life
- Low Dropout Voltage: 140 mV (Typical) @ 150 mA
- High Output Voltage Accuracy: ±0.4% (Typical)
- Standard or Custom Output Voltages
- Power-Saving Shutdown Mode
- ERROR Output Can Be Used as a Low Battery Detector or Processor Reset Generator
- Fast Shutdown Reponse Time: 60 µs (Typical)
- Overcurrent and Overtemperature Protection
- Space-Saving 5-Pin SOT-23A Package
- Pin Compatible Upgrades for Bipolar Regulators
- Standard Output Voltage Options:
 - 1.8V, 2.5V, 2.6V, 2.7V, 2.8V, 2.85V, 3.0V, 3.3V, 5.0V

Applications

- Battery Operated Systems
- Portable Computers
- Medical Instruments
- Instrumentation
- Cellular / GSMS / PHS Phones
- Pagers

Typical Application



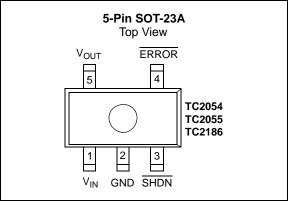
General Description

The TC2054, TC2055 and TC2186 are high accuracy (typically $\pm 0.4\%$) CMOS upgrades for older (bipolar) low dropout regulators. Designed specifically for battery-operated systems, the devices' total supply current is typically 55 μ A at full load (20 to 60 times lower than in bipolar regulators).

The devices' key features include low noise operation, low dropout voltage – typically 45 mV (TC2054); 90 mV (TC2055); and 140 mV (TC2186) at full load - and fast response to step changes in load. An error output (ERROR) is asserted when the devices are out-of-regulation (due to a low input voltage or excessive output current). Supply current is reduced to 0.5 μ A (maximum) and both V_{OUT} and ERROR are disabled when the shutdown input is low. The devices also incorporate overcurrent and overtemperature protection.

The TC2054, TC2055 and TC2186 are stable with a low esr ceramic output capacitor of 1 μ F and have a maximum output current of 50 mA, 100 mA and 150 mA, respectively. This LDO Family also features a fast response time (60 μ s typically) when released from shutdown.

Package Type



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Input Voltage	6.5V
Output Voltage	(-0.3) to (V _{IN} + 0.3)
Operating Temperature	40°C < T _J < 125°C
Storage Temperature	65°C to +150°C
Maximum Voltage on Any Pin	V _{IN} +0.3V to -0.3V

ELECTRICAL SPECIFICATIONS

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods my affect device reliability.

Electrical Specifications: Unless otherwise noted, $V_{IN} = V_R + 1V$, $I_L = 100 \ \mu$ A, $C_L = 3.3 \ \mu$ F, $\overline{SHDN} > V_{IH}$, $T_A = +25^{\circ}$ C. BOLDFACE type specifications apply for junction temperature of -40^{\circ}C to +125^{\circ}C.						
Parameter	Sym	Min	Тур	Max	Units	Conditions
Input Operating Voltage	V _{IN}	2.7	—	6.0	V	Note 1
Maximum Output Current		50	_	_	mA	TC2054

input operating voltage	* IN	2.1		0.0	v	
Maximum Output Current	IOUT _{MAX}	50	_	_	mA	TC2054
		100	_	_		TC2055
		150	_	—		TC2186
Output Voltage	V _{OUT}	V _R - 2.0%	$V_R \pm 0.4\%$	V _R + 2.0%	V	Note 2
V _{OUT} Temperature	TCV _{OUT}	_	20	_	ppm/°C	Note 3
Coefficient		_	40	—		
Line Regulation	ΔV _{OUT} / ΔV _{IN}	—	0.05	0.5	%	$(V_R + 1V) \le V_{IN} \le 6V$
Load Regulation	ΔV _{OUT} /	-1.0	0.33	+1.0	%	TC2054;TC2055 $I_L = 0.1$ mA to IOUT _{MAX}
	V _{OUT}	-2.0	0.43	+2.0		TC2186 $I_L = 0.1 \text{ mA to IOUT}_{MAX}$
						Note 6
Dropout Voltage, Note 7	$V_{IN} - V_{OUT}$	—	2	—	mV	I _L = 100 μA
		—	45	70		I _L = 50 mA
		—	90	140		TC2015; TC2185 I _L = 100 mA
		—	140	210		TC2185 I _L = 150 mA
						Note 7
Supply Current	I _{IN}	—	55	80	μA	$\overline{\text{SHDN}} = V_{\text{IH}}, I_{\text{L}} = 0$
Shutdown Supply Current	I _{INSD}	_	0.05	0.5	μA	SHDN = 0V
Power Supply Rejection Ratio	PSRR	_	50	_	dB	$F_{RE} \le 100 \text{ kHz}$
Output Short Circuit Current	I _{OUTSC}	160	300	_	mA	V _{OUT} = 0V

Note 1: The minimum V_{IN} has to meet two conditions: $V_{IN} = 2.7V$ and $V_{IN} = V_R + V_{DROPOUT}$.

2: V_R is the regulator output voltage setting. For example: $V_R = 1.8V$, 2.7V, 2.8V, 2.85V, 3.0V, 3.3V.

$$V_{OUT} = \frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^6}{V_{OUTMAX} + V_{OUTMIN} \times 10^6}$$

4: 5:

- $\frac{V_{OUT} \times \Delta T}{V_{OUT} \times \Delta T}$
- **6:** Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 1.0 mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
- 7: Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value at a 1V differential.
- 8: Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I_{MAX} at V_{IN} = 6V for T = 10 ms.
- **9:** The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e. T_A, T_J, θ_{JA}).
- **10:** Hysteresis voltage is referenced by V_R.
- **11:** Time required for V_{OUT} to reach 95% of V_R (output voltage setting), after V_{SHDN} is switched from 0 to V_{IN} .

ELECTRICAL SPECIFICATIONS (CONTINUED)

Electrical Specifications: Unless otherwise noted, $V_{IN} = V_R + 1V$, $I_L = 100 \mu A$, $C_L = 3.3 \mu F$, $\overline{SHDN} > V_{IH}$, $T_A = +25^{\circ}C$. **BOLDFACE** type specifications apply for junction temperature of -40°C to +125°C.

BOLDFACE type specifications apply for junction temperature of -40°C to +125°C.						
Parameter	Sym	Min	Тур	Max	Units	Conditions
Thermal Regulation	$\Delta V_{\text{OUT/}} \Delta P_{\text{D}}$		0.04		V/W	Note 8
Thermal Shutdown Die Temperature	T _{SD}	_	160	_	°C	
Output Noise	eN	_	600	_	nV / √Hz	$I_L = I_{OUT_{MAX}}, F = 10 \text{ kHz}$
Response Time (from Shutdown Mode)	t _R	_	60	_	μs	V _{IN} = 4V C _{IN} = 1 μF, C _{OUT} = 10 μF I _L = 0.1 mA, Note 11
SHDN Input						
SHDN Input High Threshold	VIH	60	—	_	%V _{IN}	V _{IN} = 2.5V to 6.0V
SHDN Input Low Threshold	V _{IL}	_	—	15	%V _{IN}	V _{IN} = 2.5V to 6.0V
ERROR OUTPUT						
Minimum V _{IN} Operating Voltage	V _{INMIN}	1.0	—	—	V	I _{OL} = 0.1 mA
Output Logic Low Voltage	V _{OL}	_	—	400	mV	1 mA Flows to ERROR, $I_{OL} = 1$ mA, $V_{IN} = 2V$
ERROR Threshold Voltage	V _{TH}	—	0.95 x V _R	_	V	See Figure 4-2
ERROR Positive Hysteresis	V _{HYS}		50		mV	Note 10
V _{OUT} to ERROR Delay	t _{DELAY}		2	_	ms	V_{OUT} from $V_{R} = 3V$ to 2.8V
Resistance from ERROR to GND	RERROR	_	126	_	Ω	V _{DD} = 2.5V, V _{OUT} = 2.5V

Note 1: The minimum V_{IN} has to meet two conditions: $V_{IN} = 2.7V$ and $V_{IN} = V_R + V_{DROPOUT}$.

 V_R is the regulator output voltage setting. For example: V_R = 1.8V, 2.7V, 2.8V, 2.85V, 3.0V, 3.3V. 2:

3:
$$TCV_{OUT} = \frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^{6}}{V_{OUT} \times \Delta T}$$

5: $V_{OUT} \times \Delta T$

5:

Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested 6: over a load range from 1.0 mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.

Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal 7: value at a 1V differential.

8: Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I_{MAX} at V_{IN} = 6V for T = 10 ms.

9: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e. T_A , T_J , θ_{JA}).

10: Hysteresis voltage is referenced by V_R .

11: Time required for V_{OUT} to reach 95% of V_R (output voltage setting), after V_{SHDN} is switched from 0 to V_{IN}.

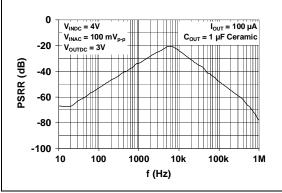
TEMPERATURE CHARACTERISTICS

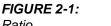
Electrical Specifications: Unless otherwise noted, $V_{DD} = +2.7V$ to +6.0V and $V_{SS} = GND$.						
Parameters	Sym	Min	Тур	Max	Units	Conditions
Temperature Ranges:						
Extended Temperature Range	T _A	-40	—	+125	°C	
Operating Temperature Range	T _A	-40	—	+125	°C	
Storage Temperature Range	T _A	-65	—	+150	°C	
Thermal Package Resistances:						
Thermal Resistance, 5L-SOT-23	θ_{JA}	_	255	_	°C/W	

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, $V_{IN} = V_R + 1V$, $I_L = 100 \ \mu$ A, $C_{OUT} = 3.3 \ \mu$ F, SHDN > V_{IH} , $T_A = +25^{\circ}$ C.





Power Supply Rejection

Ratio.

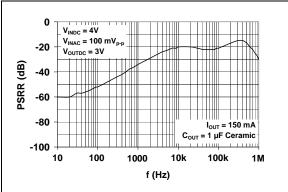
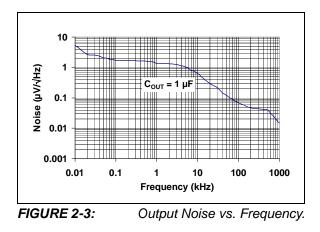


FIGURE 2-2: Power Supply Rejection Ratio.



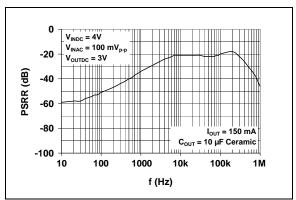


FIGURE 2-4: Power Supply Rejection Ratio.

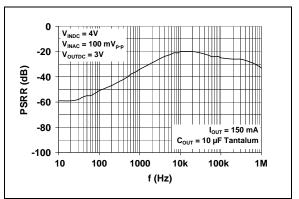
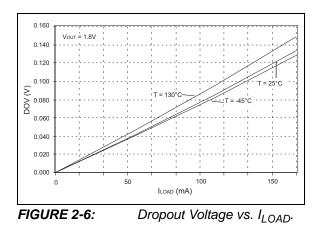


FIGURE 2-5: Power Supply Rejection Ratio.



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Note: Unless otherwise indicated, $V_{IN} = V_R + 1V$, $I_L = 100 \ \mu$ A, $C_{OUT} = 3.3 \ \mu$ F, $\overline{SHDN} > V_{IH}$, $T_A = +25^{\circ}C$.

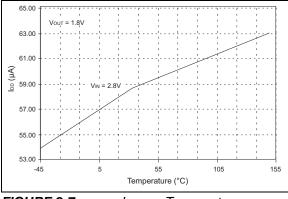


FIGURE 2-7:

I_{DD} vs. Temperature.

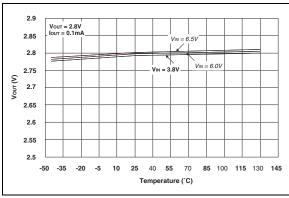


FIGURE 2-8: Temperature.

Output Voltage vs.

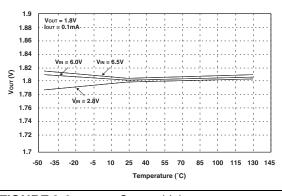


FIGURE 2-9: Output Voltage vs. Temperature.

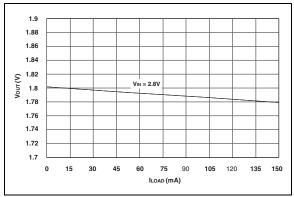


FIGURE 2-10: Output Voltage vs. Output Current.

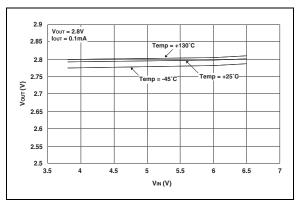


FIGURE 2-11: Output Voltage vs. Supply Voltage.

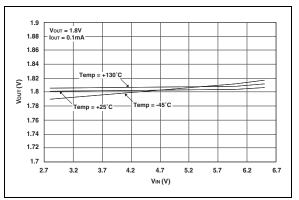
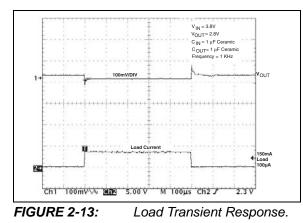


FIGURE 2-12: Dropout Voltage vs. Supply Voltage.

Note: Unless otherwise indicated, $V_{IN} = V_R + 1V$, $I_L = 100 \ \mu$ A, $C_{OUT} = 3.3 \ \mu$ F, $\overline{SHDN} > V_{IH}$, $T_A = +25^{\circ}C$.



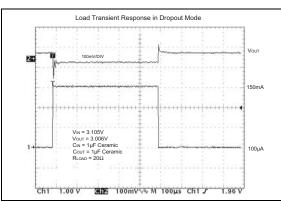
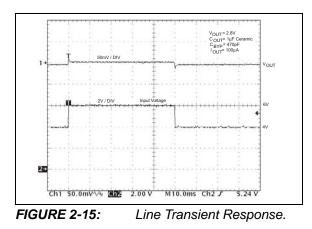


FIGURE 2-14: Load Transient Response in Dropout Mode.



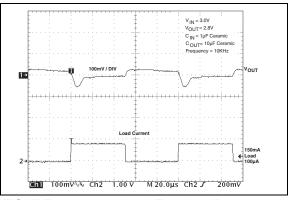
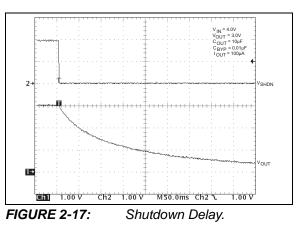
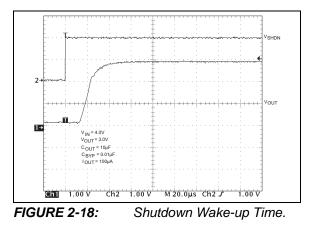


FIGURE 2-16: Load Tr

Load Transient Response.





Note: Unless otherwise indicated, V_{IN} = V_R + 1V, I_L = 100 μ A, C_{OUT} = 3.3 μ F, SHDN > V_{IH}, T_A = +25°C.

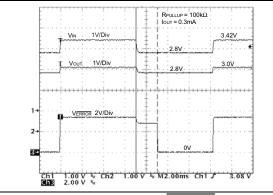


FIGURE 2-19: V_{OUT} to ERROR Delay.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

Pin Number	Symbol	Description
1	V _{IN}	Unregulated supply input.
2	GND	Ground terminal.
3	SHDN	Shutdown control input. The regulator is fully enabled when a logic high is applied to this input. The regulator enters shutdown when a logic low is applied to this input. During shutdown, output voltage falls to zero, ERROR is open circuited and supply current is reduced to $0.5 \ \mu$ A (maximum).
4	ERROR	Out-of-Regulation Flag. (Open-drain output). This output goes low when V_{OUT} is out-of-tolerance by approximately -5%.
5	V _{OUT}	Regulated voltage output.

TABLE 3-1:PIN FUNCTION TABLE

3.1 Unregulated Supply Input (V_{IN})

Connect the unregulated input supply to the V_{IN} pin. If there is a large distance between the input supply and the LDO regulator, some input capacitance is necessary for proper operation. A 1 μF capacitor, connected from V_{IN} to ground, is recommended for most applications.

3.2 Ground Terminal (GND)

Connect the unregulated input supply ground return to GND. Also connect one side of the 1 μ F typical input decoupling capacitor close to this pin and one side of the output capacitor C_{OUT} to this pin.

3.3 Shutdown Control Input (SHDN)

The regulator is fully enabled when a logic-high is applied to SHDN. The regulator enters shutdown when a logic-low is applied to this input. During shutdown, the output voltage falls to zero and the supply current is reduced to $0.5 \ \mu A$ (maximum).

3.4 Out-of-Regulation Flag (ERROR)

The open-drain ERROR flag provides indication that the regulator output voltage is not in regulation. The ERROR pin will be low when the output is typically below 5% of its specified value.

3.5 Regulated Voltage Output (V_{OUT})

Connect the output load to V_{OUT} of the LDO. Also connect one side of the LDO output decoupling capacitor as close as possible to the V_{OUT} pin.

4.0 DETAILED DESCRIPTION

The TC2054, TC2055 and TC2186 are precision fixed output voltage regulators. (If an adjustable version is desired, refer to the TC1070/TC1071/TC1187 data sheet (DS21353). Unlike bipolar regulators, the TC2054, TC2055 and TC2186 supply current does not increase with load current. In addition, V_{OUT} remains stable and within regulation over the entire 0 mA to maximum output current operating load range.

Figure 4-1 shows a typical application circuit. The regulator is enabled any time the shutdown input (SHDN) is at or above V_{IH}, and shutdown (disabled) when SHDN is at or below V_{IL}. SHDN may be controlled by a CMOS logic gate, or I/O port of a microcontroller. If the SHDN input is not required, it should be connected directly to the input supply. While in shutdown, supply current decreases to 0.05 μ A (typical), V_{OUT} falls to zero volts, and ERROR is open-circuited.

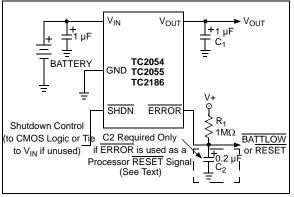


FIGURE 4-1:

Typical Application Circuit.

4.1 ERROR Open-Drain Output

ERROR is driven low whenever V_{OUT} falls out of regulation by more than -5% (typical). This condition may be caused by low input voltage, output current limiting or thermal limiting. The ERROR threshold is 5% below rated V_{OUT} regardless of the programmed output voltage value (e.g. ERROR = V_{OL} at 4.75V (typical) for a 5.0V regulator and 2.85V (typical) for a 3.0V regulator). ERROR output operation is shown in Figure 4-2.

Note that $\overline{\text{ERROR}}$ is active when V_{OUT} falls to V_{TH}, and inactive when V_{OUT} rises above V_{TH} by V_{HYS}.

As shown in Figure 4-1, ERROR can be used as a battery low flag or as a processor RESET signal (with the addition of timing capacitor C₂). R₁ x C₂ should be chosen to maintain ERROR below V_{IH} of the processor RESET input for at least 200 ms to allow time for the system to stabilize. Pull-up resistor R₁ can be tied to V_{OUT}, V_{IN} or any other voltage less than (V_{IN} + 0.3V). The ERROR pin sink current is self-limiting to approximately 18 mA.

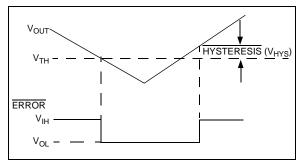


FIGURE 4-2: Error Output Operation.

4.2 Output Capacitor

A 1 μF (minimum) capacitor from V_{OUT} to ground is required. The output capacitor should have an effective series resistance of 0.01 Ω . to 5 Ω for V_{OUT} = 2.5V, and 0.05 Ω . to 5 Ω for V_{OUT} < 2.5V. Ceramic, tantalum and aluminum electrolytic capacitors can be used. (Since many aluminum electrolytic capacitors freeze at approximately -30°C, solid tantalums are recommended for applications operating below -25°C). When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

4.3 Input Capacitor

A 1 μF capacitor should be connected from V_{IN} to GND if there is more than 10 inches of wire between the regulator and this AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitors can be used (since many electrolytic aluminum capacitors freeze at approximately -30°C, solid tantalum are recommended for applications operating below -25°C). When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

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5.0 THERMAL CONSIDERATIONS

5.1 Thermal Shutdown

Integrated thermal protection circuitry shuts the regulator off when the die temperature exceeds approximately 160°C. The regulator remains off until the die temperature cools to approximatley 150°C.

5.2 Power Dissipation

The amount of power the regulator dissipates is primarily a function of input and output voltage, and output current.

Equation 5-1 is used to calculate worst case power dissipation:

EQUATION 5-1:

$$\begin{split} P_D &\approx (V_{INMAX} - V_{OUTMIN}) I_{LOADMAX} \end{split}$$

 Where:

$$\begin{split} P_D &= & \text{Worst-case actual power dissipation} \\ V_{\text{INMAX}} &= & \text{Maximum voltage on } V_{\text{IN}} \\ V_{\text{OUTMIN}} &= & \text{Minimum regulator output voltage} \\ I_{\text{LOADMAX}} &= & \text{Maximum output (load) current} \end{split}$$

The maximum allowable power dissipation (Equation 5-2) is a function of the maximum ambient temperature ($T_{A_{MAX}}$), the maximum allowable die temperature (125 °C) and the thermal resistance from junction-to-air (θ_{JA}). The 5-Pin SOT-23A package has a θ_{JA} of approximately 220°C/Watt when mounted on a typical two layer FR4 dielectric copper clad PC board.

EQUATION 5-2:

$$P_{DMAX} = \frac{T_{JMAX} - T_{AMAX}}{\theta_{JA}}$$

Where all terms are previously defined.

Equation 5-1 can be used in conjunction with Equation 5-2 to ensure regulator thermal operation is within limits. For example:

Given:

 $\begin{array}{ll} V_{INMAX} &= 3.0V + 10\% \\ V_{OUTMIN} &= 2.7V - 2.5\% \\ I_{LOADMAX} &= 40 \mbox{ mA} \\ T_{AMAX} &= +55^{\circ}\mbox{C} \end{array}$

Find:

1. Actual power dissipation

2. Maximum allowable dissipation

Actual power dissipation:

$$P_D = (V_{INMAX} - V_{OUTMIN})I_{LOADMAX}$$

= [(3.0 × 1.1) - (2.7 × 0.975)]40 × 10⁻³
= 26.7mW

Maximum allowable power dissipation:

 $P_{DMAX} = \frac{T_{JMAX} - T_{AMAX}}{\theta_{JA}}$ $= \frac{125 - 55}{220}$ = 318 mW

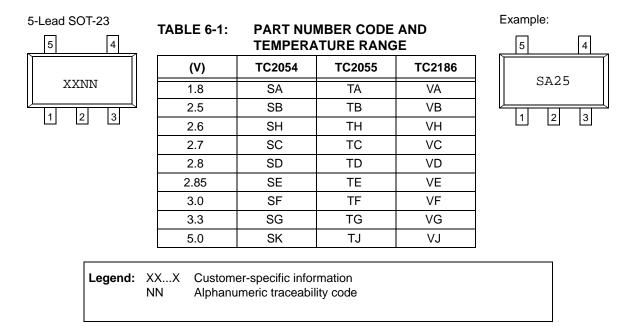
In this example, the TC2054 dissipates a maximum of only 26.7 mW; far below the allowable limit of 318 mW. In a similar manner, Equation 5-1 and Equation 5-2 can be used to calculate maximum current and/or input voltage limits.

5.3 Layout Considerations

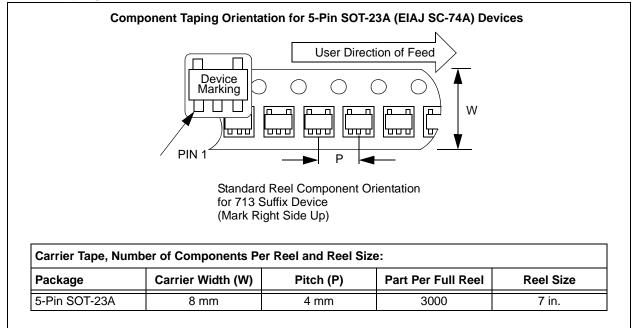
The primary path of heat conduction out of the package is via the package leads. Therefore, layouts having a ground plane, wide traces at the pads, and wide power supply bus lines combine to lower θ_{JA} and, therefore, increase the maximum allowable power dissipation limit.

6.0 PACKAGING INFORMATION

6.1 Package Marking Information



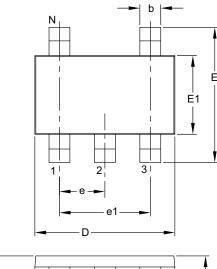
6.2 Taping Information

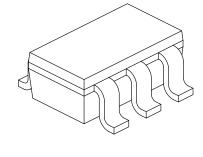


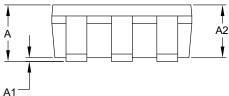
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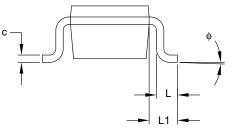
5-Lead Plastic Small Outline Transistor (CT) [SOT-23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging









	Units		MILLIMETERS	3	
Dime	ension Limits	MIN	NOM	MAX	
Number of Pins	N		5		
Lead Pitch	е		0.95 BSC		
Outside Lead Pitch	e1		1.90 BSC		
Overall Height	А	0.90	-	1.45	
Molded Package Thickness	A2	0.89	-	1.30	
Standoff	A1	0.00	-	0.15	
Overall Width	E	2.20	-	3.20	
Molded Package Width	E1	1.30	-	1.80	
Overall Length	D	2.70	-	3.10	
Foot Length	L	0.10	-	0.60	
Footprint	L1	0.35	-	0.80	
Foot Angle	φ	0°	-	30°	
Lead Thickness	С	0.08	-	0.26	
Lead Width	b	0.20	_	0.51	

Notes:

- 1. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
- 2. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-091B

APPENDIX A: REVISION HISTORY

Revision D (September 2009)

The following is the list of modifications:

- 1. Added the 2.6V, and 5.0V option in Table 6-1 in Section 6.0 "Packaging Information".
- 2. Updated the package outline drawing.
- 3. Added 2.6V option to **Product Identification System** section.

Revision C (May 2006)

The following is the list of modifications:

- 1. Added overtemperature to bullet for overcurrent protection in Features and General Description verbiage.
- Added "Thermal Shutdown Die Temperature" to the Electrical Specifications table. Changed condition for "Minimum V_{IN} Operating Voltage".
- 3. Added Temperature Characteristics Table.
- 4. Added Section 5.1 "Thermal Shutdown".
- 5. Updated the package outline drawing.

Revision B (May 2002)

• Data Sheet converted to Microchip standards.

Revision A (May 2001)

• Original Release of this Document under Telcom.

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PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NOX</u>	<u>x x xxxx</u>	Examples:
Device Out Volt		a) TC2054-1.8VCTTR: 5LD SOT-23-A, 1.8V, Tape and Reel.
Voit	aye Kanye	b) TC2054-2.85VCTTR: 5LD SOT-23-A, 2.85V, Tape and Reel.
Device:	TC2054: 50 mA LDO with Shutdown and ERROR Output TC2055: 100 mA LDO with Shutdown and ERROR Output TC2186: 150 mA LDO with Shutdown and ERROR Output	c) TC2054-3.3VCTTR: 5LD SOT-23-A, 3.3V, Tape and Reel.
Output Voltage:	XX = 1.8V	a) TC2055-1.8VCTTR: 5LD SOT-23-A, 1.8V, Tape and Reel.
Oulput Voltage.	$\begin{array}{l} xx = 2.5V \\ xx = 2.6V \end{array}$	b) TC2055-2.85VCTTR: 5LD SOT-23-A, 2.85V, Tape and Reel.
	XX = 2.7V $XX = 2.8V$ $XX = 2.85V$ $XX = 2.85V$	c) TC2055-3.0VCTTR: 5LD SOT-23-A, 3.0V, Tape and Reel.
	$\begin{array}{rcl} XX &=& 3.0V\\ XX &=& 3.3V\\ XX &=& 5.0V \end{array}$	a) TC2186-1.8VCTTR: 5LD SOT-23-A, 1.8V, Tape and Reel.
Temperature Range:	V = -40°C to +125°C	b) TC2186-2.8VCTTR: 5LD SOT-23-A, 2.8V, Tape and Reel.
Package:	CTTR = Plastic Small Outline Transistor (SOT-23), 5-lead, Tape and Reel	

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